

Title: HIGH-DENSITY MULTICHP MODULE PACKAGE
Inventor's Name: HO et al
Application No.: New Application
Docket No.: 025796-00014

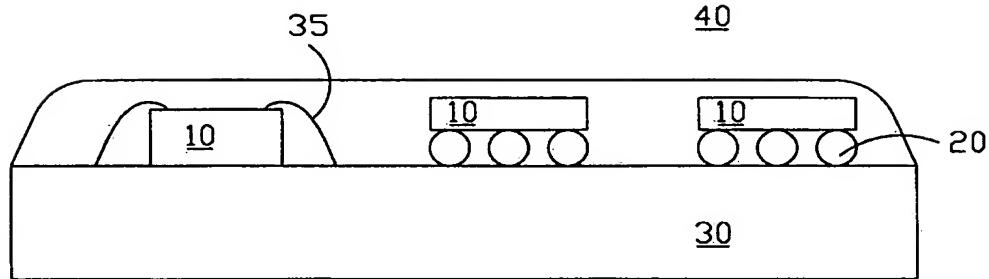


FIG.1(Prior Art)

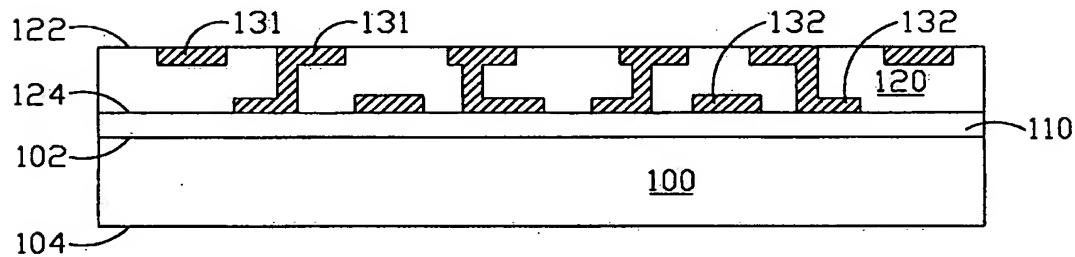


FIG.2

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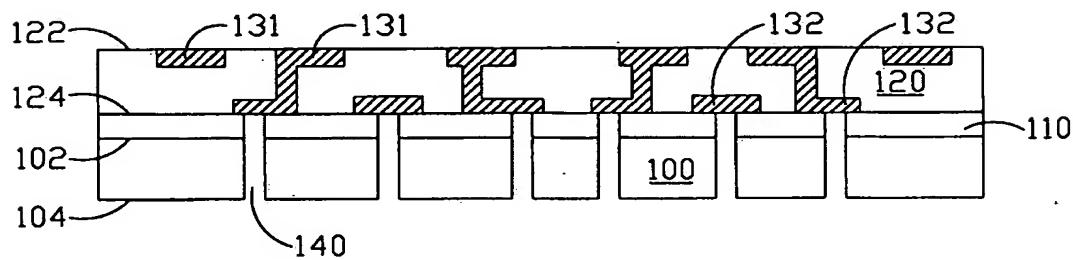


FIG.3

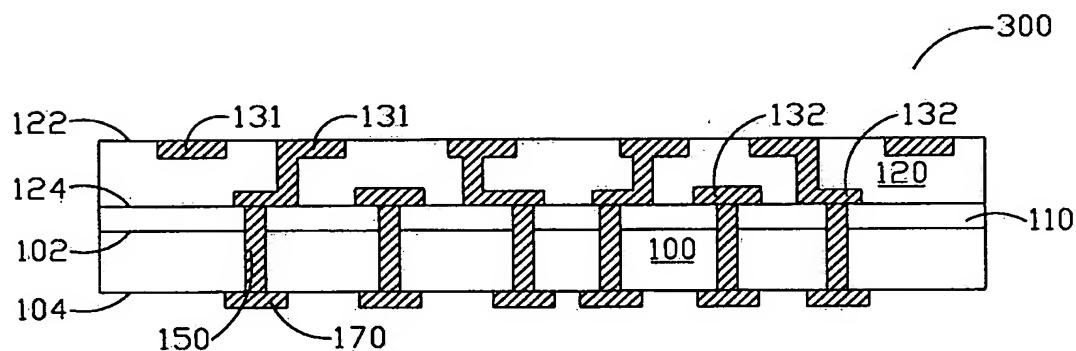


FIG.4

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Application No.: New Application
Docket No.: 025796-00014

5

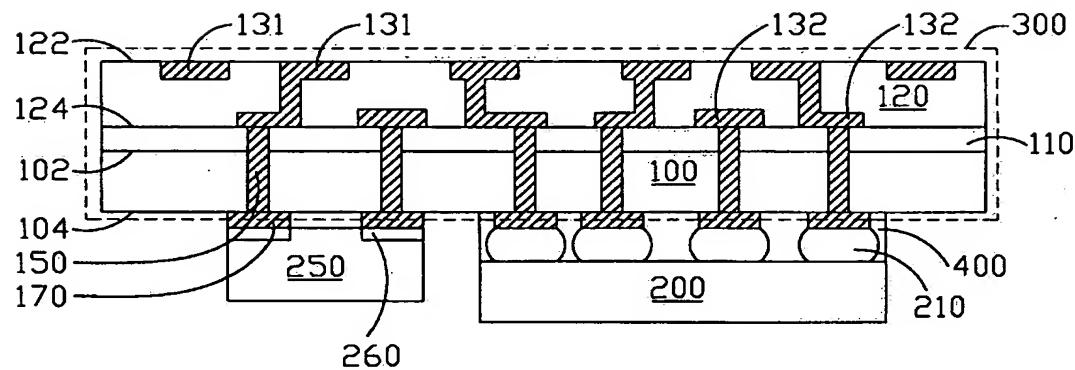
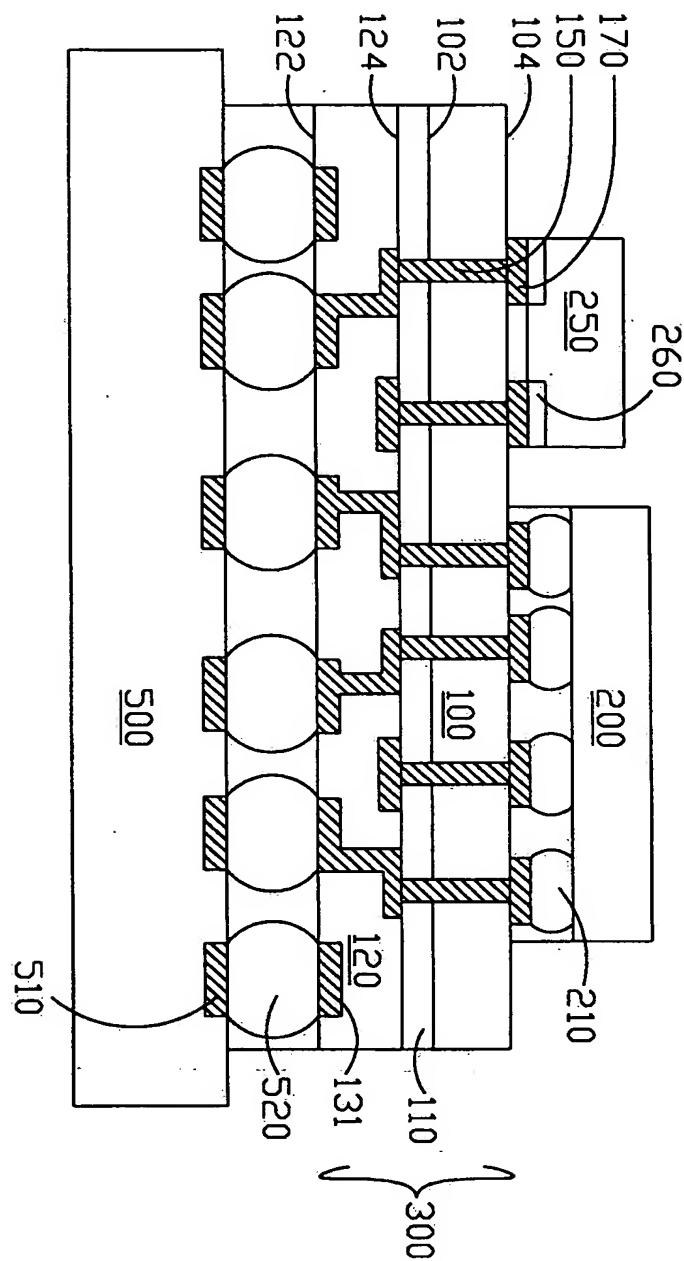


FIG.5

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FIG.6



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FIG. 7

